

Product Summary

V_{RRM} (V)	I_O (A)	V_F (typ) @ 125°C (V)	I_R (MAX) @ V_{RRM} (mA)
45	12	0.38	0.3

Description

The SBR12U45LH uses SBR patented technology that offers ultra-low V_F to reduce forward power loss and improve efficiency. Encapsulated in the new PDI-5SP package with a 0.75mm low height profile and protruding leads for easy soldering, it is especially suited for use as a bypass diode in solar panels.

Applications

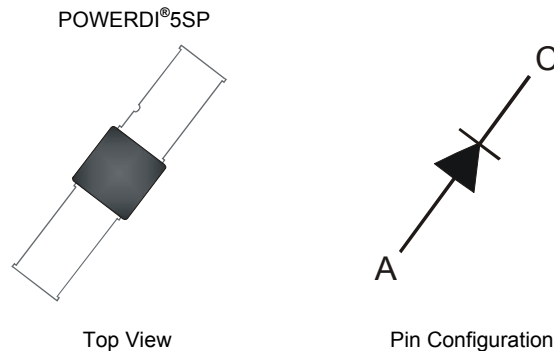
- Solar Bypass Diode

Features

- Designed as bypass diodes for solar panels
- Low profile height (0.75mm) and 9mm protruding leads, enabling the package to be integrated within the solar glass panel
- Selectively rated for 200°C maximum junction temperature for high thermal reliability and excellent high temperature stability
- Patented Super Barrier Rectifier technology
- Ultra low forward voltage drop to minimize forward power losses
- Very low reverse leakage to ensures maximum efficiency of solar panel
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

- Case: POWERDI[®]5SP
- Case Material: Molded Plastic, UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Weight: 0.199 grams (approximate)

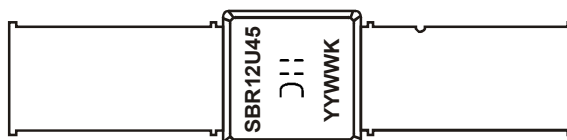


Ordering Information (Note 4)

Part Number	Case	Packaging
SBR12U45LH-13	POWERDI5SP	3500 Tape & Reel

- Notes:
- EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 - See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 - Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 - For packaging details, go to our website at <http://www.diodes.com/products/packages.html>

Marking Information



SBR12U45 = Product Type Marking Code
 J11 = Manufacturers' Code Marking
 YYWWK = Date Code Marking
 YY = Last Two Digits of Year (ex: 11 for 2011)
 WW = Week Code (01 ~ 53)
 K = Factory Designator

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_{RM}	45	V
Average Rectified Output Current	I_O	12	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	300	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	$R_{\theta JA}$	66	°C/W
Operating Temperature Range	$V_R \leq 80\% V_{RRM}$	-65 to +150	°C
	DC Forward Mode (Note 7)	≤ 175	
	DC Forward Mode (Note 8)	≤ 200	
Storage Temperature Range	T_{STG}	-65 to +175	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop	V_F	—	0.40	0.48	V	$I_F = 10A, T_J = +25^\circ C$
		—	0.42	0.50		$I_F = 12A, T_J = +25^\circ C$
		—	0.38	0.45		$I_F = 12A, T_J = +125^\circ C$
Leakage Current (Note 6)	I_R	—	70	200	μA	$V_R = 40V, T_J = +25^\circ C$
		—	90	300		$V_R = 45V, T_J = +25^\circ C$
		—	19	—	mΩ	$V_R = 45V, T_J = +125^\circ C$
		—	60	—		$V_R = 45V, T_J = +150^\circ C$

Notes: 5. FR-4 PCB, 2oz. Copper, minimum recommended pad layout per <http://www.diodes.com.pdf>.
6. Short duration pulse test used to minimize self-heating effect.
7. Max junction temperature 175°C guaranteed for 2 hours at maximum output.
8. Max junction temperature 200°C guaranteed for 2 hours at maximum output.

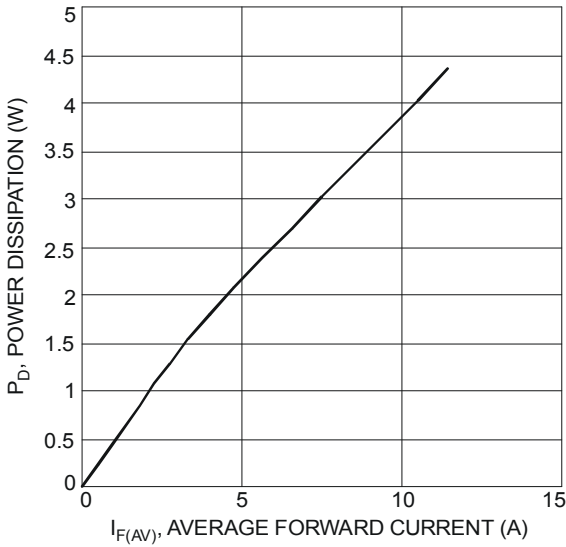


Fig. 1 Forward Power Dissipation

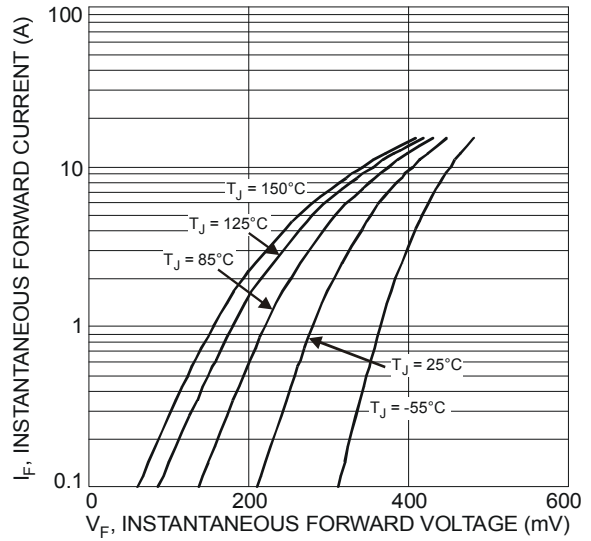


Fig. 2 Typical Forward Characteristics

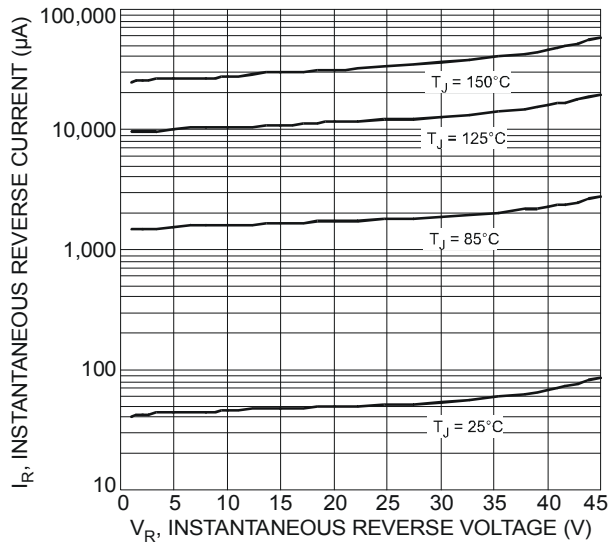


Fig. 3 Typical Reverse Characteristics

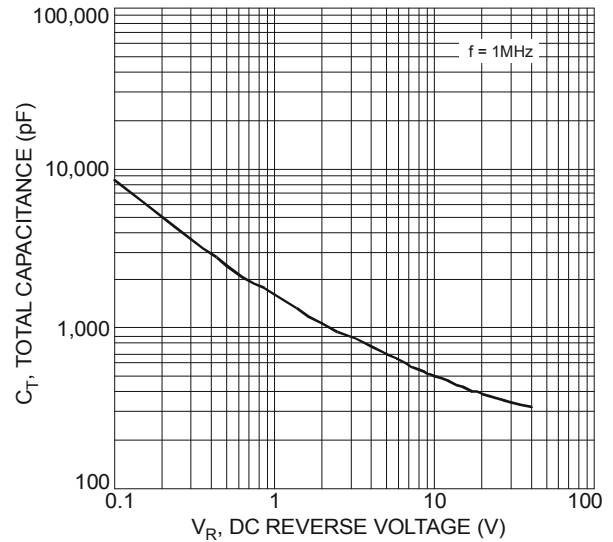


Fig. 4 Total Capacitance vs. Reverse Voltage

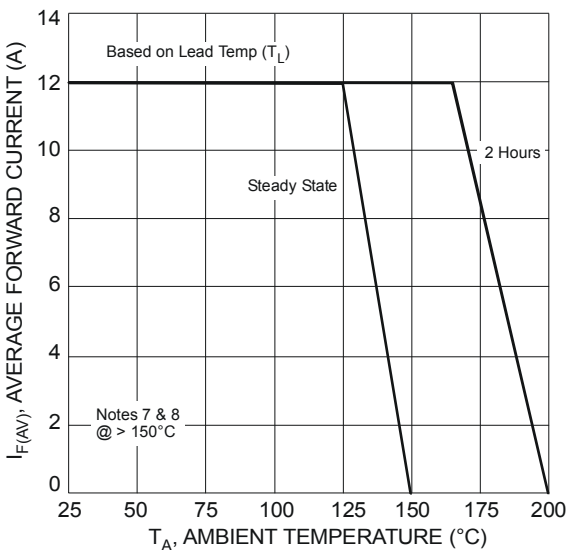


Fig. 5 Forward Current Derating Curve

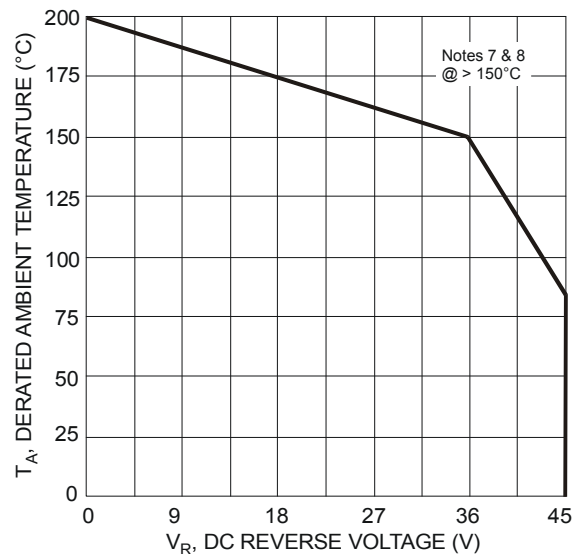
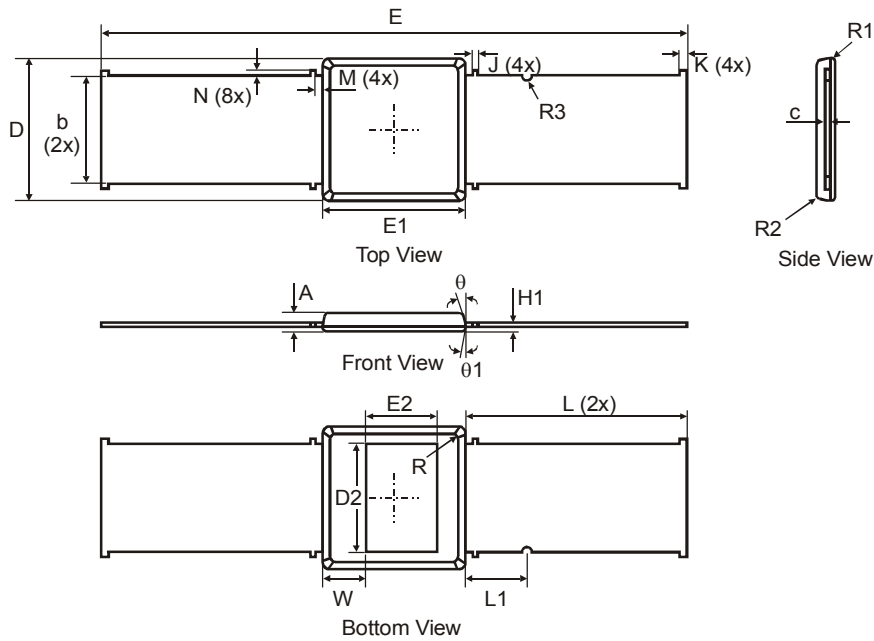


Fig. 6 Operating Temperature Derating

Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



POWERDI®5SP			
Dim	Min	Max	Typ
A	—	0.75	0.736
c	0.155	0.195	—
b	4.30	4.50	4.40
D	5.70	5.90	5.80
D2	—	—	4.40
E	23.6	24.0	23.8
E1	5.70	5.90	5.80
E2	—	—	2.90
H1	0.19	0.21	0.20
L	—	—	9.00
L1	—	—	2.50
W	1.63	1.97	1.80
J	—	—	0.20
K	—	—	0.30
M	—	—	0.03
N	0	0.20	—
R	—	—	0.40
R1	—	—	0.15
R2	—	—	0.25
R3	—	—	0.40
θ	4°	12°	—
θ2	0°	8°	—
All Dimensions in mm			

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